

# LC717A10AJ

## Capacitance-Digital-Converter LSI for Electrostatic Capacitive Touch Sensors

### Overview

The LC717A10AJ is a high-performance and low-cost capacitance-digital-converter LSI for electrostatic capacitive touch sensor, especially focused on usability.

It has 16 channels capacitance-sensor input. This makes it ideal for use in the products that need many switches. Since the calibration function and the judgment of ON/OFF are automatically performed in LSI internal, it can make development time more short. A detection result (ON/OFF) for each input can be read out by the serial interface (I<sup>2</sup>C™ compatible bus or SPI).

Also, measurement value of each input can be read out as 8-bit digital data. Moreover, gain and other parameters can be adjusted using serial interface.

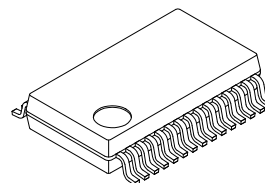
### Features

- Detection System: Differential Capacitance Detection (Mutual Capacitance Type)
- Input Capacitance Resolution: Can Detect Capacitance Changes in the Femto Farad Order
- Measurement Interval (16 Differential Inputs):
  - ◆ 30 ms (Typ) (at Initial Configuration)
  - ◆ 6 ms (Typ) (at Minimum Interval Configuration)
- External Components for Measurement: Not Required
- Current Consumption:
  - ◆ 570  $\mu$ A (Typ) ( $V_{DD} = 2.8$  V)
  - ◆ 1.3 mA (Typ) ( $V_{DD} = 5.5$  V)
- Supply Voltage: 2.6 V to 5.5 V
- Detection Operations: Switch
- Interface: I<sup>2</sup>C Compatible Bus or SPI Selectable



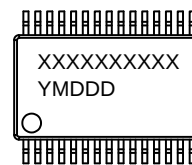
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**SSOP30 (225 mil)  
CASE 565AZ**

### MARKING DIAGRAM



XXXXXX = Specific Device Code  
Y = Year  
M = Month  
DDD = Additional Traceability Data

### ORDERING INFORMATION

See detailed ordering and shipping information on page 11 of this data sheet.

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## Specifications

**Table 1. ABSOLUTE MAXIMUM RATINGS** ( $T_A = 25^\circ\text{C}$ ,  $V_{SS} = 0\text{ V}$ )

| Parameter           | Symbol             | Ratings                | Unit             | Remarks                                                      |
|---------------------|--------------------|------------------------|------------------|--------------------------------------------------------------|
| Supply Voltage      | $V_{DD}$           | -0.3 to +6.5           | V                |                                                              |
| Input Voltage       | $V_{IN}$           | -0.3 to $V_{DD} + 0.3$ | V                | (Note 1)                                                     |
| Output Voltage      | $V_{OUT}$          | -0.3 to $V_{DD} + 0.3$ | V                | (Note 2)                                                     |
| Power Dissipation   | $P_{d\text{ max}}$ | 160                    | mW               | $T_A = +105^\circ\text{C}$ , Mounted on a substrate (Note 3) |
| Storage Temperature | $T_{stg}$          | -55 to +125            | $^\circ\text{C}$ |                                                              |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Apply to  $C_{in0}$  to 15,  $C_{ref}$ ,  $C_{refAdd}$ ,  $nRST$ ,  $SCL$ ,  $SDA$ ,  $SA0$ ,  $SA1$ ,  $SCK$ ,  $SI$ ,  $nCS$ .
2. Apply to  $C_{drv}$ ,  $SDA$ ,  $SO$ ,  $INTOUT$ .
3. Single-layer glass epoxy board ( $76.1 \times 114.3 \times 1.6\text{t mm}$ ).

**Table 2. RECOMMENDED OPERATING CONDITIONS**

| Parameter                | Symbol    | Conditions | Min | Typ | Max      | Unit             | Remarks  |
|--------------------------|-----------|------------|-----|-----|----------|------------------|----------|
| Operating Supply Voltage | $V_{DD}$  |            | 2.6 | -   | 5.5      | V                |          |
| Supply Ripple + Noise    | $V_{PP}$  |            | -   | -   | $\pm 20$ | mV               | (Note 4) |
| Operating Temperature    | $T_{opr}$ |            | -40 | 25  | 105      | $^\circ\text{C}$ |          |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Inserting a high-valued capacitor and a low-valued capacitor in parallel between  $V_{DD}$  and  $V_{SS}$  is recommended. In this case, the small-valued capacitor should be at least  $0.1\text{ }\mu\text{F}$ , and is mounted near the LSI.

**Table 3. ELECTRICAL CHARACTERISTICS**

( $V_{SS} = 0\text{ V}$ ,  $V_{DD} = 2.6$  to  $5.5\text{ V}$ ,  $T_A = -40$  to  $+105^\circ\text{C}$ , Unless otherwise specified, the  $C_{drv}$  drive frequency is  $f_{CDRV} = 143\text{ kHz}$ .

Not tested at low temperature before shipment.)

| Parameter                                                  | Symbol         | Conditions                | Min  | Typ       | Max       | Unit          | Remarks      |
|------------------------------------------------------------|----------------|---------------------------|------|-----------|-----------|---------------|--------------|
| Capacitance Detection Resolution                           | N              |                           | -    | -         | 8         | bit           |              |
| Output Noise RMS                                           | $N_{RMS}$      | Minimum gain setting      | -    | -         | $\pm 1.0$ | LSB           | (Notes 5, 7) |
| Input Offset Capacitance Adjustment Range                  | $C_{offRANGE}$ |                           | -    | $\pm 8.0$ | -         | pF            | (Notes 5, 7) |
| Input Offset Capacitance Adjustment Resolution             | $C_{offRESO}$  |                           | -    | 8         | -         | bit           |              |
| $C_{in}$ Offset Drift                                      | $C_{inDRIFT}$  | Minimum gain setting      | -    | -         | $\pm 8$   | LSB           | (Note 5)     |
| $C_{in}$ Detection Sensitivity                             | $C_{inSENSE}$  | Minimum gain setting      | 0.04 | -         | 0.12      | LSB/ff        | (Note 6)     |
| $C_{in}$ Pin Leak Current                                  | $I_{Cin}$      | $C_{in} = \text{Hi-Z}$    | -    | $\pm 25$  | $\pm 500$ | nA            |              |
| $C_{in}$ Allowable Parasitic Input Capacitance             | $C_{inSUB}$    | $C_{in}$ against $V_{SS}$ | -    | -         | 30        | pF            | (Notes 5, 7) |
| $C_{drv}$ Drive Frequency                                  | $f_{CDRV}$     |                           | 100  | 143       | 186       | kHz           |              |
| $C_{drv}$ Pin Leak Current                                 | $I_{CDRV}$     | $C_{drv} = \text{Hi-Z}$   | -    | $\pm 25$  | $\pm 500$ | nA            |              |
| $nRST$ Minimum Pulse Width                                 | $t_{NRST}$     |                           | 1    | -         | -         | $\mu\text{s}$ |              |
| Power-on Reset Time                                        | $t_{POR}$      |                           | -    | -         | 20        | ms            |              |
| Power-on Reset Operation Condition: Hold Time              | $t_{POROP}$    |                           | 10   | -         | -         | ms            | (Note 5)     |
| Power-on Reset Operation Condition: Input Voltage          | $V_{POROP}$    |                           | -    | -         | 0.1       | V             | (Note 5)     |
| Power-on Reset Operation Condition: Power Supply Rise Rate | $t_{VDD}$      | 0 V to $V_{DD}$           | 1    | -         | -         | V/ms          | (Note 5)     |

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**Table 3. ELECTRICAL CHARACTERISTICS** (continued)

( $V_{SS} = 0\text{ V}$ ,  $V_{DD} = 2.6\text{ to }5.5\text{ V}$ ,  $T_A = -40\text{ to }+105^\circ\text{C}$ , Unless otherwise specified, the Cdrv drive frequency is  $f_{CDRV} = 143\text{ kHz}$ .  
Not tested at low temperature before shipment.)

| Parameter              | Symbol        | Conditions                                                       | Min          | Typ | Max          | Unit          | Remarks      |
|------------------------|---------------|------------------------------------------------------------------|--------------|-----|--------------|---------------|--------------|
| Pin Input Voltage      | $V_{IH}$      | High input                                                       | $0.8 V_{DD}$ | –   | –            | V             | (Notes 5, 8) |
|                        | $V_{IL}$      | Low input                                                        | –            | –   | $0.2 V_{DD}$ |               |              |
| Pin Output Voltage     | $V_{OH}$      | High output<br>( $I_{OH} = +3\text{ mA}$ )                       | $0.8 V_{DD}$ | –   | –            | V             | (Note 9)     |
|                        | $V_{OL}$      | Low output<br>( $I_{OL} = -3\text{ mA}$ )                        | –            | –   | $0.2 V_{DD}$ |               |              |
| SDA Pin Output Voltage | $V_{OL} I^2C$ | SDA Low output<br>( $I_{OL} = -3\text{ mA}$ )                    | –            | –   | 0.4          | V             |              |
| Pin Leak Current       | $I_{LEAK}$    |                                                                  | –            | –   | $\pm 1$      | $\mu\text{A}$ | (Note 10)    |
| Current Consumption    | $I_{DD}$      | When initial setting<br>and non-touch<br>$V_{DD} = 2.8\text{ V}$ | –            | 570 | 700          | $\mu\text{A}$ | (Notes 5, 7) |
|                        |               | When initial setting<br>and non-touch<br>$V_{DD} = 5.5\text{ V}$ | –            | 1.3 | 1.6          | mA            |              |
|                        | $I_{STBY}$    | During Sleep process                                             | –            | –   | 1            | $\mu\text{A}$ | (Note 7)     |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Design-guaranteed values (not tested before shipment).
6. Measurements conducted using the test mode in the LSI.
7.  $T_A = +25^\circ\text{C}$ .
8. Apply to nRST, SCL, SDA, SA0, SA1, SCK, SI, nCS.
9. Apply to Cdrv, SO, INTOUT.
10. Apply to nRST, SCL, SDA, SA0, SA1, SCK, SI, nCS.

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**Table 4. I<sup>2</sup>C COMPATIBLE BUS TIMING CHARACTERISTICS**

(V<sub>SS</sub> = 0 V, V<sub>DD</sub> = 2.6 to 5.5 V, T<sub>A</sub> = -40 to +105°C, Not tested at low temperature before shipment.)

| Parameter                           | Symbol                          | Pin Name | Conditions | Min | Typ | Max | Unit | Remarks   |
|-------------------------------------|---------------------------------|----------|------------|-----|-----|-----|------|-----------|
| SCL Clock Frequency                 | f <sub>SCL</sub>                | SCL      |            | –   | –   | 400 | kHz  |           |
| START Condition Hold Time           | t <sub>HD;STA</sub>             | SCL, SDA |            | 0.6 | –   | –   | μs   |           |
| SCL Clock Low Period                | t <sub>LOW</sub>                | SCL      |            | 1.3 | –   | –   | μs   |           |
| SCL Clock High Period               | t <sub>HIGH</sub>               | SCL      |            | 0.6 | –   | –   | μs   |           |
| Repeated START Condition Setup Time | t <sub>SU;STA</sub>             | SCL, SDA |            | 0.6 | –   | –   | μs   | (Note 11) |
| Data Hold Time                      | t <sub>HD;DAT</sub>             | SCL, SDA |            | 0   | –   | 0.9 | μs   |           |
| Data Setup Time                     | t <sub>SU;DAT</sub>             | SCL, SDA |            | 100 | –   | –   | ns   | (Note 11) |
| SDA, SCL Rise/Fall Time             | t <sub>r</sub> / t <sub>f</sub> | SCL, SDA |            | –   | –   | 300 | ns   | (Note 11) |
| STOP Condition Setup Time           | t <sub>SU;STO</sub>             | SCL, SDA |            | 0.6 | –   | –   | μs   |           |
| STOP-to-START Bus Release Time      | t <sub>BUF</sub>                | SCL, SDA |            | 1.3 | –   | –   | μs   | (Note 11) |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

11. Design-guaranteed values (not tested before shipment).

**Table 5. SPI BUS TIMING CHARACTERISTICS**

(V<sub>SS</sub> = 0 V, V<sub>DD</sub> = 2.6 to 5.5 V, T<sub>A</sub> = -40 to +105°C, Not tested at low temperature before shipment.)

| Parameter                                | Symbol                          | Pin Name     | Conditions | Min | Typ | Max | Unit | Remarks   |
|------------------------------------------|---------------------------------|--------------|------------|-----|-----|-----|------|-----------|
| SCK Clock Frequency                      | f <sub>SCK</sub>                | SCK          |            | –   | –   | 5   | MHz  |           |
| SCK Clock Low Time                       | t <sub>LOW</sub>                | SCK          |            | 90  | –   | –   | ns   | (Note 12) |
| SCK Clock High Time                      | t <sub>HIGH</sub>               | SCK          |            | 90  | –   | –   | ns   | (Note 12) |
| Input Signal Rise/Fall Time              | t <sub>r</sub> / t <sub>f</sub> | nCS, SCK, SI |            | –   | –   | 300 | ns   | (Note 12) |
| nCS Setup Time                           | t <sub>SU;NCS</sub>             | nCS, SCK     |            | 90  | –   | –   | ns   | (Note 12) |
| SCK Clock Setup Time                     | t <sub>SU;SCK</sub>             | nCS, SCK     |            | 90  | –   | –   | ns   | (Note 12) |
| Data Setup Time                          | t <sub>SU;SI</sub>              | SCK, SI      |            | 20  | –   | –   | ns   | (Note 12) |
| Data Hold Time                           | t <sub>HD;SI</sub>              | SCK, SI      |            | 30  | –   | –   | ns   | (Note 12) |
| nCS Hold Time                            | t <sub>HD;NCS</sub>             | nCS, SCK     |            | 90  | –   | –   | ns   | (Note 12) |
| SCK Clock Hold Time                      | t <sub>HD;SCK</sub>             | nCS, SCK     |            | 90  | –   | –   | ns   | (Note 12) |
| nCS Standby Pulse Width                  | t <sub>CPH</sub>                | nCS          |            | 90  | –   | –   | ns   | (Note 12) |
| Output High Impedance Time from nCS      | t <sub>CHZ</sub>                | nCS, SO      |            | –   | –   | 80  | ns   | (Note 12) |
| Output Data Determination Time           | t <sub>v</sub>                  | SCK, SO      |            | –   | –   | 80  | ns   | (Note 12) |
| Output Data Hold Time                    | t <sub>HD;SO</sub>              | SCK, SO      |            | 0   | –   | –   | ns   | (Note 12) |
| Output Low Impedance Time from SCK Clock | t <sub>CLZ</sub>                | SCK, SO      |            | 0   | –   | –   | ns   | (Note 12) |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

12. Design-guaranteed values (not tested before shipment).

### Power-On Reset (POR)

When power is turned on, power-on reset is enabled inside the LSI and its state is released after a certain power-on reset time,  $t_{POR}$ . Power-on reset operation condition: Power supply rise rate  $t_{VDD}$  must be at least 1 V/ms.

Since INTOUT pin changes from “High” to “Low” at the same time as the released of power-on reset, it is possible to verify the timing of release of power-on reset externally.

During power-on reset,  $C_{in}$ ,  $C_{ref}$  and  $C_{refAdd}$  are unknown.

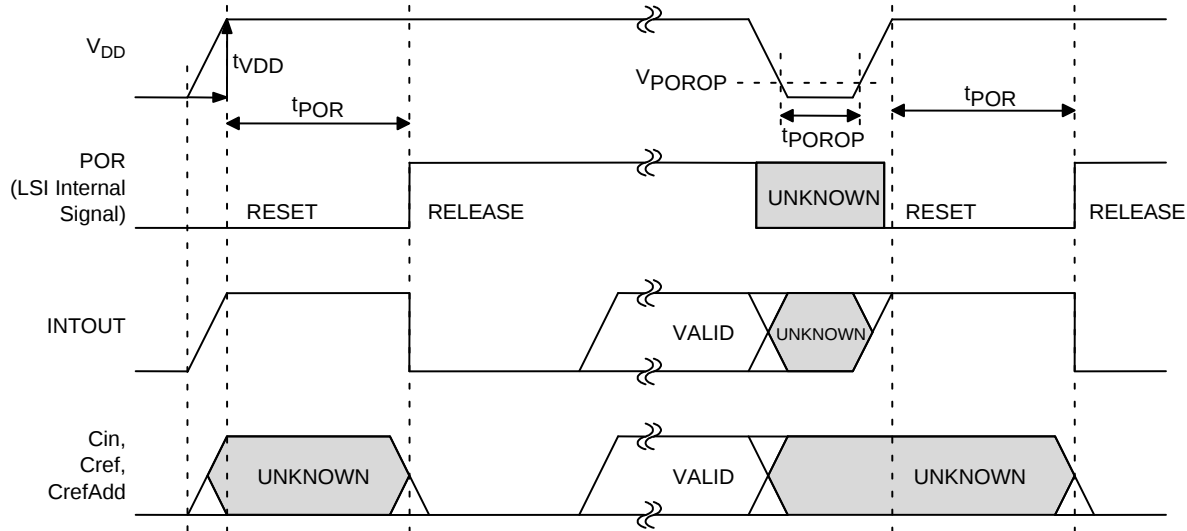


Figure 1.

### I<sup>2</sup>C Compatible Bus Data Timing

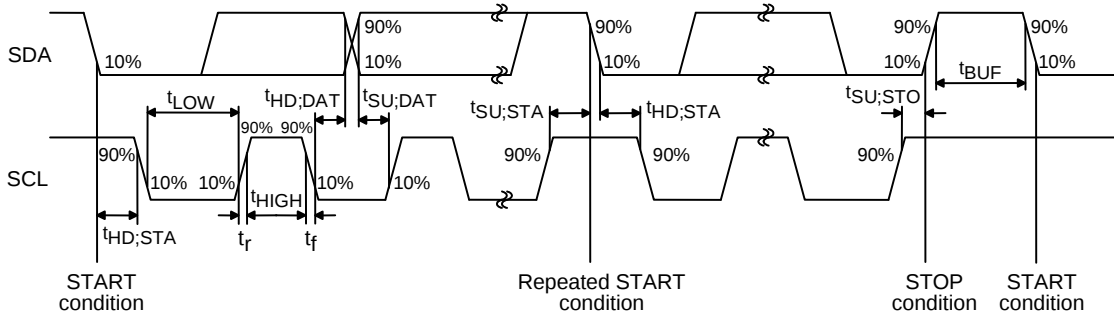


Figure 2.

### I<sup>2</sup>C Compatible Bus Communication Formats

- Write format (data can be written into sequentially incremented addresses)



Figure 3.

- Read format (data can be read from sequentially incremented addresses)

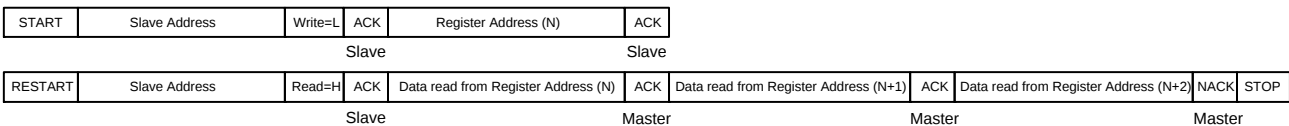


Figure 4.

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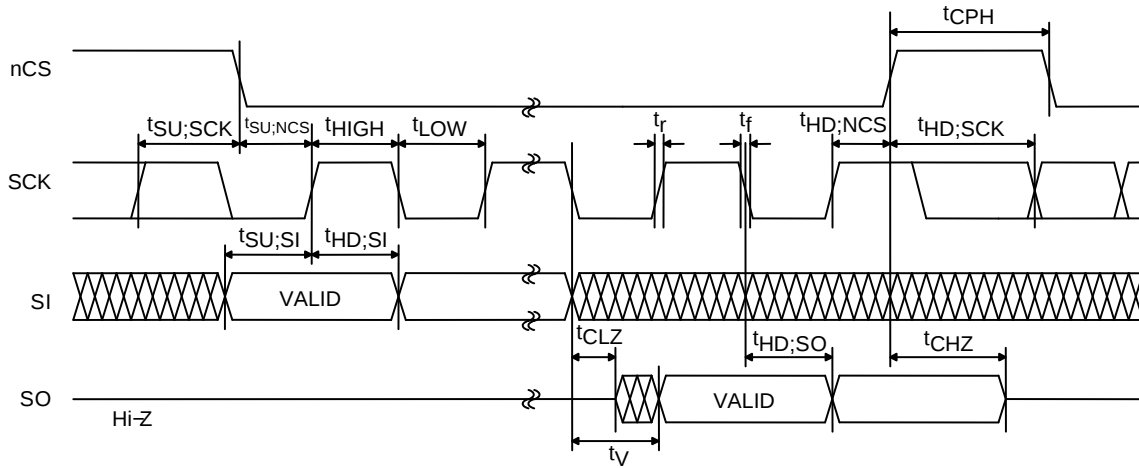
## I<sup>2</sup>C Compatible Bus Slave Address

Selection of four kinds of addresses is possible through the SA0 and SA1 terminals.

**Table 6.**

| SA1 Pin Input | SA0 Pin Input | 7-bit Slave Address | Binary Notation   | 8-bit Slave Address |
|---------------|---------------|---------------------|-------------------|---------------------|
| Low           | Low           | 0x16                | 00101100b (Write) | 0x2C                |
|               |               |                     | 00101101b (Read)  | 0x2D                |
| Low           | High          | 0x17                | 00101110b (Write) | 0x2E                |
|               |               |                     | 00101111b (Read)  | 0x2F                |
| High          | Low           | 0x18                | 00110000b (Write) | 0x30                |
|               |               |                     | 00110001b (Read)  | 0x31                |
| High          | High          | 0x19                | 00110010b (Write) | 0x32                |
|               |               |                     | 00110011b (Read)  | 0x33                |

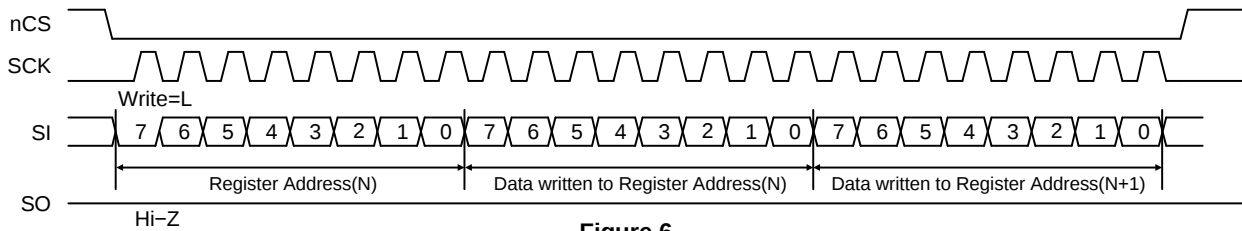
## SPI Data Timing (SPI Mode 0 / Mode 3)



**Figure 5.**

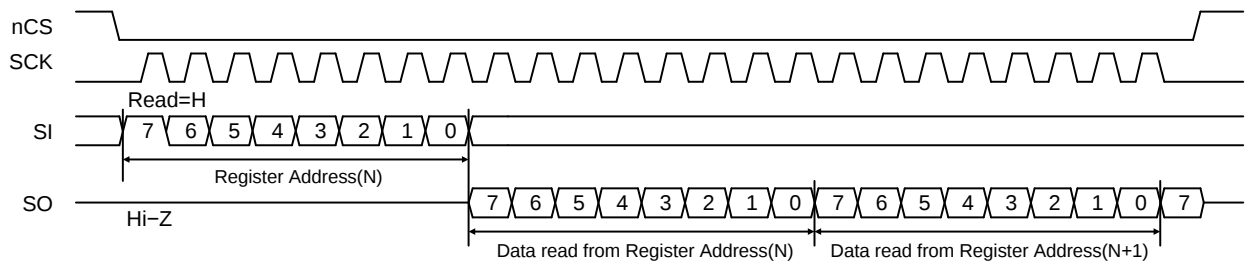
## SPI Communication Formats (Example of Mode 0)

- Write format (data can be written into sequentially incremented addresses while preserving nCS = L)



**Figure 6.**

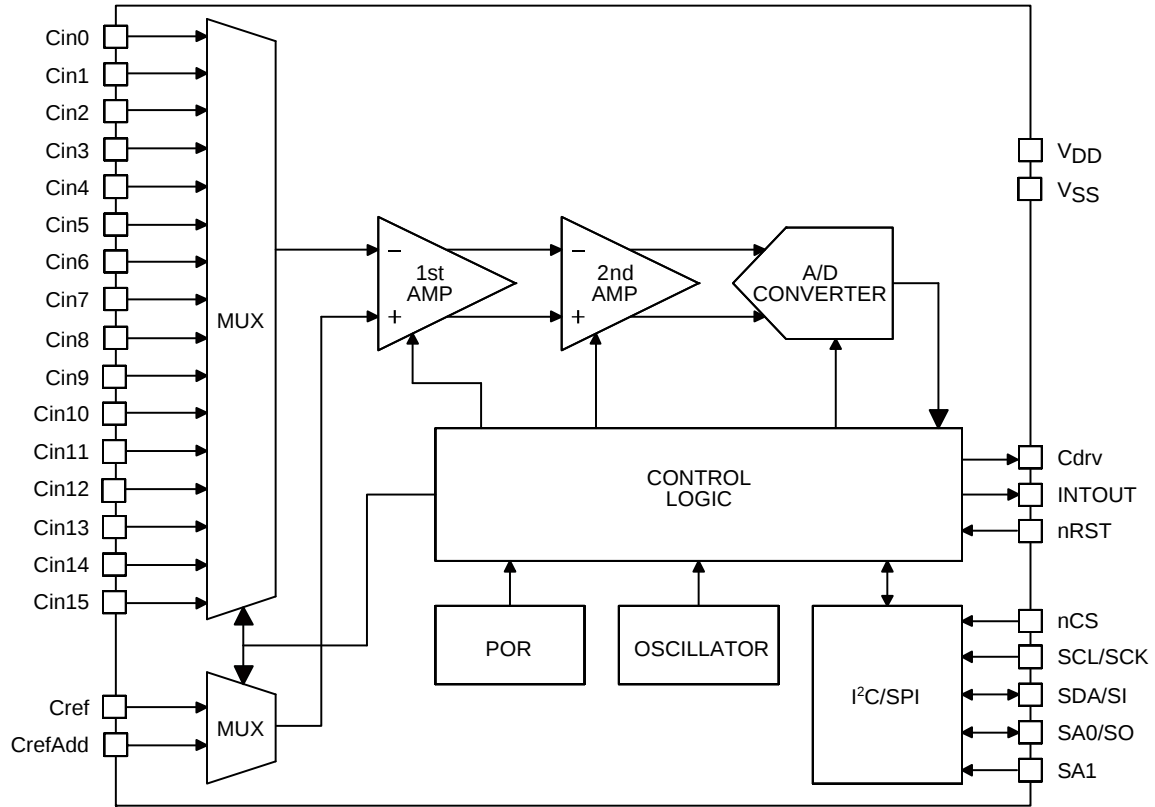
- Read format (data can be read from sequentially incremented addresses while preserving nCS = L)



**Figure 7.**

# LC717A10AJ

## Block Diagram



**Figure 8. Simplified Block Diagram**

LC717A10AJ is capacitance-digital-converter LSI capable of detecting changes in capacitance in the order of femto Farads. It consists of an oscillation circuit that generates the system clock, a power-on reset circuit that resets the system when the power is turned on, a multiplexer that selects the input channels, a two-stage amplifier that

detects the changes in the capacitance and outputs analog-amplitude values, a A/D converter that converts the analog-amplitude values into digital data, an I²C compatible bus or a SPI that enables serial communication with external devices and a control logic that controls the entire chip.

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## Pin Assignment

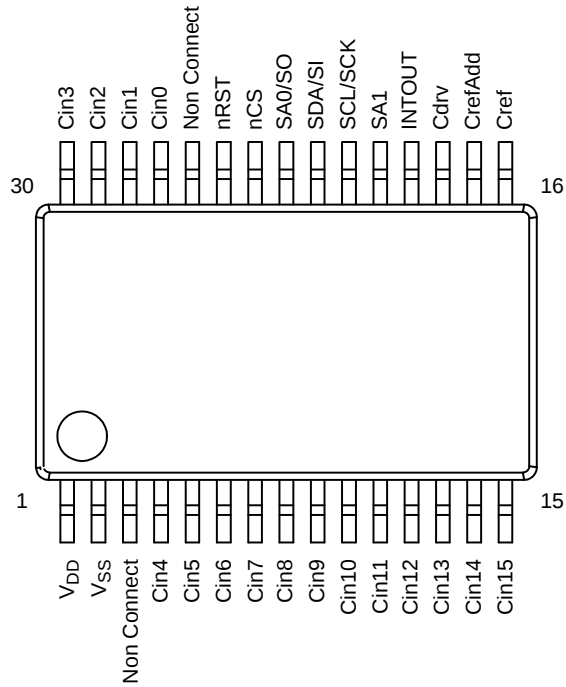


Figure 9. Pin Assignment (Top View)

Table 7. PIN ASSIGNMENT

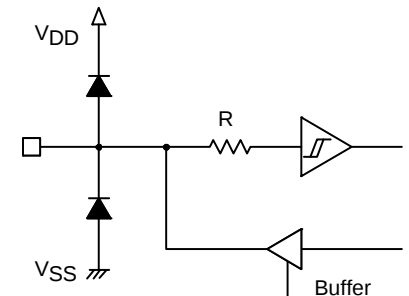
| Pin No. | Pin Name              | Pin No. | Pin Name              |
|---------|-----------------------|---------|-----------------------|
| 1       | V <sub>DD</sub>       | 16      | Cref                  |
| 2       | V <sub>SS</sub>       | 17      | CrefAdd               |
| 3       | Non Connect (Note 13) | 18      | Cdrv                  |
| 4       | Cin4                  | 19      | INTOUT                |
| 5       | Cin5                  | 20      | SA1                   |
| 6       | Cin6                  | 21      | SCL/SCK               |
| 7       | Cin7                  | 22      | SDA/SI                |
| 8       | Cin8                  | 23      | SA0/SO                |
| 9       | Cin9                  | 24      | nCS                   |
| 10      | Cin10                 | 25      | nRST                  |
| 11      | Cin11                 | 26      | Non Connect (Note 13) |
| 12      | Cin12                 | 27      | Cin0                  |
| 13      | Cin13                 | 28      | Cin1                  |
| 14      | Cin14                 | 29      | Cin2                  |
| 15      | Cin15                 | 30      | Cin3                  |

13. Connect to GND when mounted.

Table 8. PIN FUNCTION

| Pin Name | I/O | Pin Functions                                               | Pin Type |
|----------|-----|-------------------------------------------------------------|----------|
| Cin0     | I/O | Capacitance sensor input                                    |          |
| Cin1     | I/O | Capacitance sensor input                                    |          |
| Cin2     | I/O | Capacitance sensor input                                    |          |
| Cin3     | I/O | Capacitance sensor input                                    |          |
| Cin4     | I/O | Capacitance sensor input                                    |          |
| Cin5     | I/O | Capacitance sensor input                                    |          |
| Cin6     | I/O | Capacitance sensor input                                    |          |
| Cin7     | I/O | Capacitance sensor input                                    |          |
| Cin8     | I/O | Capacitance sensor input                                    |          |
| Cin9     | I/O | Capacitance sensor input                                    |          |
| Cin10    | I/O | Capacitance sensor input                                    |          |
| Cin11    | I/O | Capacitance sensor input                                    |          |
| Cin12    | I/O | Capacitance sensor input                                    |          |
| Cin13    | I/O | Capacitance sensor input                                    |          |
| Cin14    | I/O | Capacitance sensor input                                    |          |
| Cin15    | I/O | Capacitance sensor input                                    |          |
| Cref     | I/O | Reference capacitance input                                 |          |
| CrefAdd  | I/O | Reference capacitance input for addition                    |          |
| Cdrv     | O   | Output for capacitance sensors drive                        |          |
| INTOUT   | O   | Interrupt output                                            |          |
| SCL/SCK  | I   | Clock input (I <sup>2</sup> C) / Clock input (SPI)          |          |
| nCS      | I   | Interface selection / Chip select inverting input (SPI)     |          |
| nRST     | I   | External reset signal inverting input                       |          |
| SA1      | I   | Slave address selection (I <sup>2</sup> C)                  |          |
| SDA/SI   | I/O | Data input and output (I <sup>2</sup> C) / Data input (SPI) |          |

Table 8. PIN FUNCTION (continued)

| Pin Name        | I/O | Pin Functions                                                     | Pin Type                                                                           |
|-----------------|-----|-------------------------------------------------------------------|------------------------------------------------------------------------------------|
| SA0/SO          | I/O | Slave address selection (I <sup>2</sup> C) /<br>Data output (SPI) |  |
| V <sub>DD</sub> |     | Power supply (2.6 V to 5.5 V) (Note 14)                           |                                                                                    |
| V <sub>SS</sub> |     | Ground (Earth) (Notes 14, 15)                                     |                                                                                    |

14. Inserting a high-valued capacitor and a low-valued capacitor in parallel between V<sub>DD</sub> and V<sub>SS</sub> is recommended. In this case, the small-valued capacitor should be at least 0.1 μF, and is mounted near the LSI.

15. When V<sub>SS</sub> terminal is not grounded in battery-powered mobile equipment, detection sensitivity may be degraded.

## Details of Pin Functions

### Cin0 to Cin15

These are the capacitance-sensor-input pins. These pins are used by connecting them to the touch switch pattern. Cin and the Cdrv wire patterns should be close to each other. By doing so, Cdrv and Cin patterns are capacitively coupled. Therefore, LSI can detect capacitance change near each pattern as 8-bit digital data.

However, if the shape of each pattern or the capacitively coupled value of Cdrv is not appropriate, it may not be able to detect the capacitance change correctly.

In this LSI, there is a two-stage amplifier that detects the changes in the capacitance and outputs analog-amplitude values. Cin0 to Cin15 are connected to the inverting input of the 1<sup>st</sup> amplifier.

During measurement process, channels other than the one being measured are all in “Low” condition.

Leave the unused terminals open.

### Cref, CrefAdd

These are the reference-capacitance-input pins. These are used by connecting to the wire pattern like Cin pins or are used by connecting any capacitance between this pin and Cdrv pin.

In this LSI, there is a two-stage amplifier that detects the changes in the capacitance and outputs analog-amplitude values. Cref is connected to the non-inverting input of the 1<sup>st</sup> amplifier.

Due to the parasitic capacitance generated in the wire connections of Cin pins and their patterns, as well as the one generated between the wire patterns of Cin and Cdrv pins, Cref may not detect capacitance change of each Cin pin accurately. In this case, connect an appropriate capacitance between Cref and Cdrv to detect capacitance change accurately.

However, if the difference between the parasitic capacitance of each Cin pin is extremely large, it may not detect capacitance change in each Cin pin correctly.

CrefAdd can be used as additional terminal for Cref. Leave the CrefAdd open if not in used.

### Cdrv

It is the output pin for capacitance sensors drive. It outputs the pulse voltage which is needed to detect capacitance at Cin0 to Cin15.

Cdrv and Cin wire patterns should be close to each other so that they are capacitively coupled.

### INTOUT

It is the interrupt-output pin. It is used by connecting to a main microcomputer if necessary, and use as interrupt signal. (High Active).

Leave the terminal open if not in used.

### SCL/SCK

Clock input (I<sup>2</sup>C)/Clock input (SPI). It is the clock input pin of the I<sup>2</sup>C compatible bus or the SPI depending on the mode of operation.

### nCS

Interface selection/Chip-select-inverting input (SPI). Selection of I<sup>2</sup>C compatible bus mode or SPI mode is through this terminal. After initialization, the LSI is automatically in I<sup>2</sup>C compatible bus mode. To continually use I<sup>2</sup>C compatible bus mode, fix nCS pin to “High”. To switch to SPI mode after LSI initialization, change the nCS input “High” → “Low”. The nCS pin is used as the chip-select-inverting input pin of SPI, and SPI mode is kept until LSI is again initialized.

## LC717A10AJ

### *nRST*

It is the external-reset-signal-inverting-input pin. When nRST pin is “Low”, LSI is in the reset state.

Each pin (Cin0 to 15, Cref, CrefAdd) is “Hi-Z” during reset state.

### *SDA/SI*

Data input and output (I<sup>2</sup>C)/Data input (SPI). It is the data input and output pin of the I<sup>2</sup>C compatible bus or the data input pin of the SPI depending on the mode of operation.

### *SA0/SO*

Slave address selection (I<sup>2</sup>C)/Data output (SPI). It is the slave address selection pin of the I<sup>2</sup>C compatible bus or the data output pin of the SPI depending on the mode of operation.

### *SA1*

Slave address selection (I<sup>2</sup>C). It is the slave address selection pin of the I<sup>2</sup>C compatible bus.

When SPI mode, connect to the SA1 pin to GND.

**Table 9. ORDERING INFORMATION**

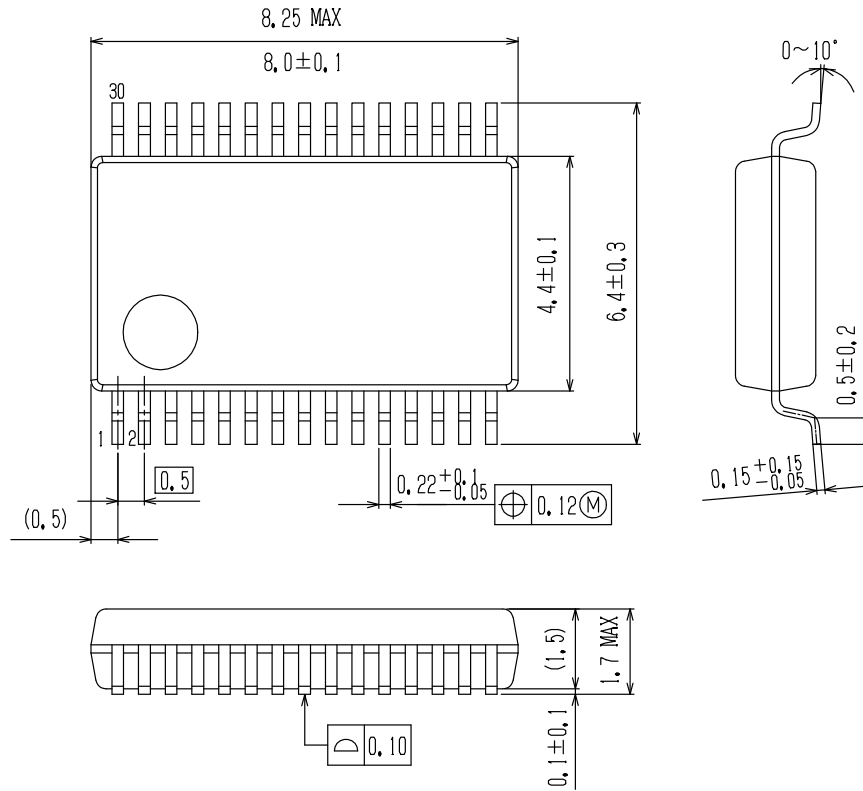
| Device        | Package                                      | Shipping (Qty / Packing) <sup>†</sup> |
|---------------|----------------------------------------------|---------------------------------------|
| LC717A10AJ-NH | SSOP30 (225 mil)<br>(Pb-Free / Halogen Free) | 1000 / Tape & Reel                    |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

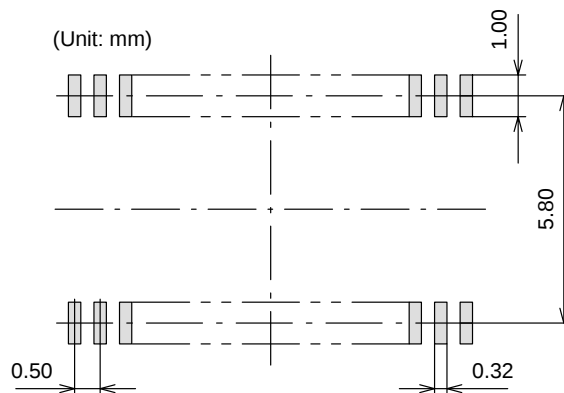
# LC717A10AJ

## PACKAGE DIMENSIONS

SSOP30 (225 mil)  
CASE 565AZ  
ISSUE A



## SOLDERING FOOTPRINT\*



NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

I<sup>2</sup>C Bus is a trademark of Philips Corporation.

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